

A1867-TX2

Dual cure epoxy adhesive: UV-Heat cure adhesive – Filters light (opaque white-tan-reddish)

DUAL CURE with high Depth UV cure and LIGHT FILTERING

PRODUCT DESCRIPTION:

- Base chemistry: epoxy only, cationic polymerization
- One component adhesive ready for use, solvent-free, UV and/or heat curing, thixotropic.

PRODUCT USE:

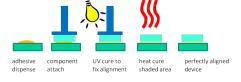
- Active alignment of components for optoelectronics and semiconductor packaging
- Module bonding with active alignment: example: bond image sensor to board or bonding VCM to lens barrel.
- Bonding of opaque substrates

FEATURES:

- Epoxy only, low thermal cure temperature with short cure time, UV-curable with LED-365nm, high adhesion, high Tg, long working life, excellent reliability performances, robust for solder reflow process
- Possible bond line thickness: 10 500 μm
- · High viscosity, excellent shape holding
- Filtred light at thickness >125 μm

INSTRUCTIONS FOR USE:

- Clean the substrates to remove contamination, dust, moisture, salt and/or oil
- 2) Dispense adhesive on substrates
- Bond substrates (with active alignment optional)
- 4) UV cure to fix alignment or to bond
- Thermal cure: to cure adhesive in shadow area and to improve adhesion of bonded parts



CURING CONDITIONS: 2 curing ways: UV + heat or heat

1) UV + Heat curing: both UV and heat are used in the curing process First step: UV cure

*Metal halide/Mercury UV: UV-A (320-400 nm), intensity: 100-1,000 mW/cm²

*or LED-365 nm, UV light intensity: 200 to 1,000 mW/cm²

LED-365 nm		Metal Halide/Mercury (UV-A: 320-400 nm)	
UV intensity (mW/cm ²) x time (sec)		UV intensity (mW/cm ²) x time (sec)	
100	100 to 150 sec	100	100 to 150 sec
or 200	50 to 75 sec	or 200	50 to 75 sec
or 500	10 to 30sec	or 500	10 to 30sec
or 1,000	5 to 15 sec	or 1,000	5 to 15 sec

<u>Second step: heat cure</u>: the adhesive is exposed to UV light first, then heat cure 80°C to 85°C for 60 minutes

2) Heat curing: heat is the only curing source, the adhesive $\underline{\text{sees no UV light}}$ 85°C for 60 to 90 minutes ,

or 90°C for 60 minutes or 100°C for 60 minutes

For heat cure, the adhesive is expected to be cured in the absence of air or sandwiched between two substrates If the adhesive surface is exposed to air during cure, surface stickiness might result.

For heat cure, the effect of humidity and air are greater for very thin film. If the adhesive layer is 10 μ m or less, then curing at temperature of 90 °C can improve performances.

Maximum depth of cure in the UV step at UV dose of 15 J/cm2: 500 micron Maximum depth of cure in the heat step or UV+heat step: 3 mm

- The actual heat cure time is dependent on the heating time of the bonded components. The time to heat up the components must be added to the total cure time of the adhesive for the process
- The recommended UV cure dose is at the adhesive; if the substrate absorbs curing light, then the actual cure time needs to be increased.
- To ensure good curing speed, the humidity should be <60% RH
- Epoxy adhesives have post cure properties. Adhesion strength tests should be conducted at least 24 hrs after part assembly.

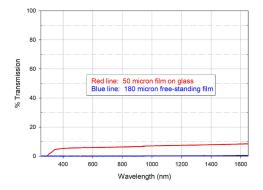
The maximum adhesion strength is achieved by HEAT cure. For best adhesion, UV fix cure should be kept at a minimum and the majority of the bonded components should be cured by HEAT



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UV-VIS and near IR spectra: light filtered

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TYPICAL PROPERTIES

Liquid

Viscosity at 25 °C, mPa.s or cps (shear rate: 10/s) 80,000 to 100,000 Thixotropic index (shear rate: 1/s over 10/s) 5 Density (g/mL) 1.3 Shelf life (-40 to -20°C): 6 months Pot life or working life (20 - 25°C): 48 hours

Cured film

Appearance of cured adhesive opaque yellow to tan

Cured film properties (continued)

Water permeability (g/m 24 hrs, 50 °C/95% RH, 75 μ m film) 2.2 x 10^{-4} Shrinkage (volume, %) 1 Hardness, shore D 85 Glass transition temperature (DMA, °C) 173

Physical properties tested at 25°C, 50% RH (ASTM D638)

Tensile strength, MPa 151 Elongation (%) 5 Young's Modulus, MPa 2,010

Operating temperature, °C -40 to 140

GENERAL USAGE INFORMATION:

Shipment: adhesive is shipped in cold pack

Storage: After receipt, cold storage at -20 °C or -40 °C in the original container is required

Before use: The cold adhesive needs to reach RT (20-25°C) before use. The container needs to sit at RT, adding heat is not allowed. Room temperature equilibration time is dependent on container size, but a 10-30 gram syringe equilibration time is approximately 30-60 minutes. Condensed water on the container must be removed prior to use

SAFETY AND HANDLING

The uncured adhesive can be cleaned from apparatus with isopropyl alcohol (IPA), methyl ethyl ketone (MEK), acetone or commercial alcohol based cleaning solution. Avoid direct skin and eye contact. Use only in well ventilated areas. Use protective clothing, **gloves and safety goggles**. Read <u>Safety Data Sheet</u> before handling.